HCP0704

Product Specifications

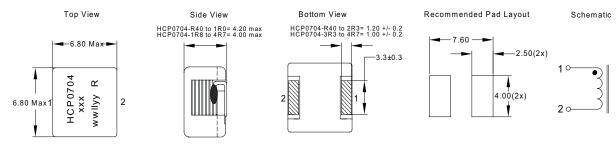
Part Number ⁶	0CL ¹ ± 25% (μH)	FLL ² Min. (μH)	I _{rms} ³ (A)	I _{sat} ⁴ @ +25 °C (A)	DCR (mΩ) @ +20 °C	K-factor⁵
HCP0704-R40-R	0.40	0.28	17	27	3.2 ±10%	383.1
HCP0704-R60-R	0.60	0.42	14	21	4.5 ±10%	313.5
HCP0704-1R0-R	1.00	0.7	12	17	6.2 ±10%	265.3
HCP0704-1R8-R	1.80	1.26	8.5	13	11.0 ±10%	202.8
HCP0704-2R3-R	2.30	1.56	7.5	11.5	16.5 ±10%	164.2
HCP0704-3R3-R	3.30	2.31	6.0	9.5	25.0 ±10%	149.9
HCP0704-4R7-R	4.70	3.29	5.0	8.0	29.5 ±10%	127.7

- 1 Open Circuit Inductance (OCL) Test Parameters: 100 kHz, 0.10 V_{rms}, 0.0 Adc
- 2 Full Load Inductance (FLL) Test Parameters: 100 kHz, 0.1 V_{rms} , I_{sat} 1
- 3 I_{rms}: DC current for an approximate temperature rise of 40 °C without core loss. Derating
- is necessary for AC currents. PCB pad layout, trace thickness and width, air-flow and proximity of other heat generating components will affect the temperature rise. It is recommended the part temperature not exceed +125 °C under worst case operating conditions verified in the end application.
- 4 I_{Sat} : Peak current for approximately 20% rolloff at +25 °C.
- 5 K-factor: Used to determine B_{p-p} for core loss (see graph). $B_{p-p} = K \star L \star \Delta I$: (Gauss), K: (K-factor of the factor of the factor) from table), L: (inductance in hH), AI (peak-to-peak ripple current in amps).

 6 Part Number Definition: HCP0704-xxx-R
- HCP0704 = Product code and size
- xxx= Inductance value in $\mu\text{H, R} =$ decimal point. If no "R" is present, then third character = # of zeros

 • "-R" suffix = RoHS compliant

Dimensions (mm)



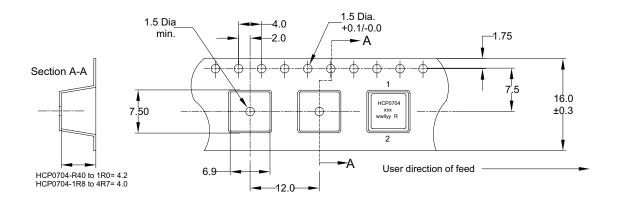
The nominal DCR test point is in the middle of the terminal

Part Marking: HCP0704 xxx =Inductance value in μH . (R = Decimal point). If no "R" is present, then last character is # of zeros wwllyy = Date code R = Revision level

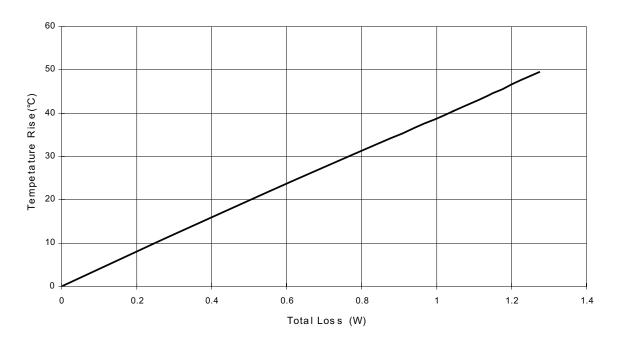
Do not route traces or vias underneath the inductor

Packaging information (mm)

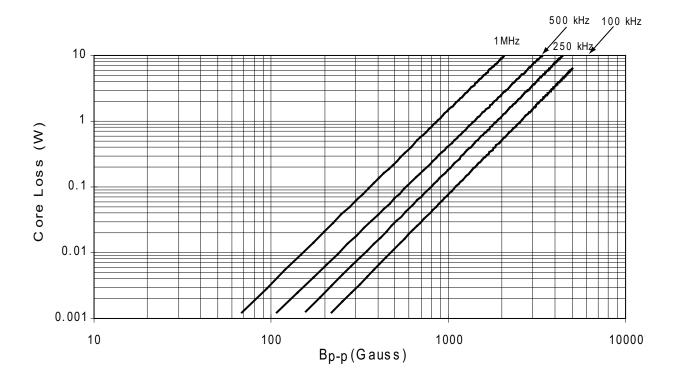
Supplied in tape and reel packaging, 1000 parts per 13" diameter reel.



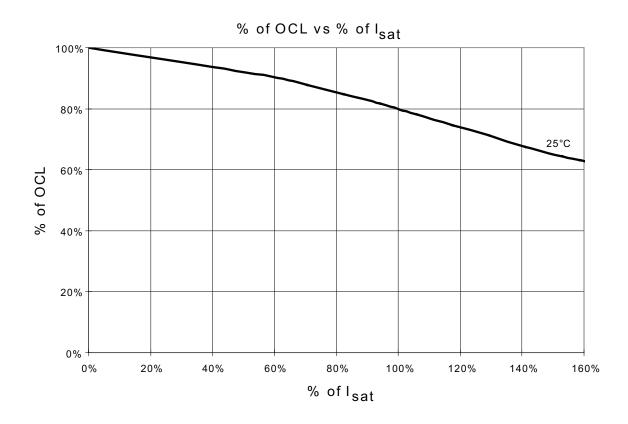
Temperature rise vs. total loss



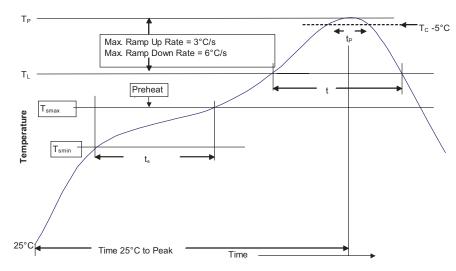
Core loss vs. B_{p-p}



Inductance characteristics



Solder reflow profile



-_{Tc-5°C} Table 1 - Standard SnPb Solder (T_C)

Package Thickness	Volume mm3 <350	Volume mm3 ≥350
<2.5mm)	235°C	220°C
≥2.5mm	220°C	220°C

Table 2 - Lead (Pb) Free Solder (T_C)

Package Thickness	Volume mm³ <350	Volume mm³ 350 - 2000	Volume mm³ >2000
<1.6mm	260°C	260°C	260°C
1.6 - 2.5mm	260°C	250°C	245°C
>2.5mm	250°C	245°C	245°C

Reference JDEC J-STD-020

Profile Feature	Standard SnPb Solder	Lead (Pb) Free Solder
Preheat and Soak • Temperature min. (T _{smin})	100°C	150°C
• Temperature max. (T _{smax})	150°C	200°C
• Time (T _{smin} to T _{smax}) (t _s)	60-120 Seconds	60-120 Seconds
Average ramp up rate T _{smax} to T _p	3°C/ Second Max.	3°C/ Second Max.
Liquidous temperature (TL) Time at liquidous (tL)	183°C 60-150 Seconds	217°C 60-150 Seconds
Peak package body temperature (Tp)*	Table 1	Table 2
Time $(t_p)^{**}$ within 5 °C of the specified classification temperature (T_c)	20 Seconds**	30 Seconds**
Average ramp-down rate (T _p to T _{smax})	6°C/ Second Max.	6°C/ Second Max.
Time 25°C to Peak Temperature	6 Minutes Max.	8 Minutes Max.

^{*} Tolerance for peak profile temperature (Tp) is defined as a supplier minimum and a user maximum.

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^{**} Tolerance for time at peak profile temperature (t_p) is defined as a supplier minimum and a user maximum.